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forming at least one blind via comprising a passage from said second surface through said dielectric layer to expose said layer of electrically conducting material;
depositing electrically conducting material in at least one of said blind vias wherein said electrically conducting layer is in electrical contact with said electrically conductive material in said at least one blind via;
removing portions of the layer of electrically conducting material to define a pattern of circuitry;
stacking a plurality of said sub-composites;
aligning said plurality of sub-composites;
joining said plurality of sub-composites such that the electrically conducting material in at least one of said blind vias makes electrical contact with the conductive pattern on an adjacent sub-composite; and
filling spaces between adjacent sub-composites with electrically insulating material.

Sub Bley
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67. (Amended) An electronic package, comprising:
a printed wiring board comprising at least two prefabricated substructures joined together, each substructure comprising a layer of dielectric material having a top surface and a bottom surface, a pattern of circuitry on one of the top surface and the bottom surface of the layer of dielectric material, and at least one passage through the dielectric layer in connection with the circuitry, the at least one passage being filled with electrically conducting material, the at least two substructures being stacked on each other such that one of the electrically conducting material filling the at least one passage and the circuitry pattern on one substructure contacts and is electrically conductively joined to one of the electrically conducting material filling the at least one passage and the circuitry pattern on another substructure; and electrically insulating material between facing substructures except between a joined filled passage and a circuitry pattern; and
a plurality of electronic components attached to the printed wiring board.
